

TITLE OF INVENTION: MICROELECTRONIC PACKAGE WITH THREE-DIMENSIONAL (3D) MONOLITHIC MEMORY DIE

ABSTRACT

Embodiments may relate to a microelectronic package. The microelectronic package may include a memory die with: a first memory cell at a first layer of the memory die; a second memory cell at a second layer of the memory die; and a via in the memory die that communicatively couples an active die with a package substrate of the microelectronic package. Other embodiments may be described or claimed.

Fig. 1